



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2026-03-03
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Floriana SAN BIAGIO	Representative title	Material Declaration Champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance\* true Legal declaration\* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSC211YCT	AYWO*US5BAAY	C	9992-ZS1A	2024-02-21
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	7	mg	Each	ECOPACK® 3
<b>Identity</b>	<b>Authority</b>			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
DSO	2 x 1.26	6	Gull wing
Comment			
Comment	WO SOT 323 6LDS		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 3rd January 2025		Response	
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen		false	
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen		true	
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.003	Die	429

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014		Response		
<b>QUERY</b>		<b>Response</b>		
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products		false		
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products		false		
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-4th February 2026				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	False

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

Other Fluorinated Substances	Response
QUERY	Response
The product is containing fluorinated substance.	False
Substance Name, CAS	

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AYWO*US5BAAY		7.0010		3999998.0	1000145.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	0.706	mg	supplier	die	Silicon(Si)	7440-21-3		0.513	mg	726629	73286				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.007	mg	9915	1000				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.139	mg	196884	19857				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.003	mg	4249	429				
				supplier	metallisation	Silver(Ag)	7440-22-4		0.001	mg	1416	143				
				supplier	metallisation	Tin(Sn)	7440-31-5		0.024	mg	33994	3429				
				supplier	Passivation	Silicon nitride(Si3N4)	12033-89-5		0.002	mg	2833	286				
				supplier	passivation	Silicon oxide	7631-86-9		0.017	mg	24079	2429				
				Leadframe	M-004 Copper and its alloys	2.579	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.517	mg	975960	359571
								supplier	alloy	Iron (Fe)	7439-89-6		0.058	mg	22489	8286
supplier	alloy	Phosphorus (P)	7723-14-0						0.001	mg	388	143				
supplier	alloy	Zinc (Zn)	7440-66-6						0.003	mg	1163	429				
Encapsulation	M-015 Other organic materials	3.376	mg	supplier	mold compound	Silica vitreous	60676-86-0		2.903	mg	859893	414714				
				supplier	mold compound	Epoxy type resin	proprietary		0.196	mg	58057	28000				
				supplier	mold compound	Biphenyl epoxy	85954-11-6		0.169	mg	50059	24143				
				supplier	mold compound	phenolic resin	proprietary		0.101	mg	29917	14429				
				supplier	mold compound	Carbon black	1333-86-4		0.007	mg	2073	1000				
Connections coating	Solder	0.340	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.340	mg	1000000	48571				